

(GB) Version:

Trade Name:	SRC HM1 RMA (Ag2) V16L
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- 1. Company Address:
 Almit GmbH
 Ph.: +49 6066 96884-0

 Dekan-Groh-Straße 4
 Fax: +49 6066 96884-18

 (D) 64720 Michelstadt near Frankfurt
- 2. Validity: This specification is specified for: Almit-Solder-Paste SRC HM1 RMA (Ag2) V16L Delivered by Almit GmbH to: ______

3. Diameter & Allowance:

Weight	500g	500g	800g	1500g	
Allowance	-0, +10g				

4. Deliverable Reel Size:

Metal Name	Solidus °C	Liquidus °C	Specific Gravity
Sn62 AG2	179	190	8.4

5. Physical Pro

Test	Characteristics	Test Methods
Metal Content	90.5 ± 1.0	IPC-TM-650 2.2.20
Silver Chromate	bestanden	IPC-TM-650 2.3.33
Copper Mirror Test	bestanden	IPC-TM-650 2.3.32
SIR (85°C, 85%, 168hr) (Ω)	≥ 1x10 ⁸	IPC-TM-650 2.6.3.3
Corrosion Test	bestanden	IPC-TM-650 2.6.15
Flux materials composition	RO	J-STD 004 1.2
Quantitative Halide	L1 < 0.5%	IPC-TM-650 2.3.35
Fluorides By Spot Test	bestanden	IPC-TM-650 2.6.35.1

6. Characterisitcs:

Composition	Components							
composition	Sn	Pb	Cu	Ag	Sb	Bi	Au	In
Standard	62.0	Rest	≤0.05	2.0	≤0.12	≤0.1	≤0.08	≤0.1
Composition	Components							
composition	AI		As	Cd	Fe	Ni	Zn	
Standard	≤0.	001	≤0.03	≤0.002	≤0.02	≤0.01	≤0.001	

7. Solder Powder Size & Distribution:

% of Sample by Weight – Nominal Size

Type	not	less than 1%	at least 80%	at most 10%
Туре	larger than	larger than	between	less than
Type 4 V16L	40 Microns	38 Microns	20 - 38 Microns	20 Microns

9. Quality and Inspection:

Inspection items are applied to each lc

Test No.	Inspection Item	Contents	Standard				
1	Appearance	Color	Comparison with Limit Specimer				
2	Weight	Net Weight	-0 ; +10 (g)				
3	Solder Powder Size	20 - 38 µm V16L	94 ≤ (wt%)				
		Pb	Rest (wt%)				
4	Motal Composition	Sn	62.0 ± 0.5 (wt%)				
4	4 Metal Composition	Ag	2.0 ± 0.2 (wt%)				
			(wt%)				
5		Flux Content	9.5 ± 0.5 (wt%)				
6		Solder Balling Test	Comparison with Limit Specimer				
7	Characteristics	Viscosity (Spiral type, 10rpm, 25°C) (IPC-650-2.4.34.3)	210000 ± 30000 (cps) 210 ± 30 (Pa•s)				
8	8	Solderability on Cu-Plate Comp					
9		Dryness	Chalk powder should be easily removed from each test specimen.				

*Straight lines of solder paste are printed on a JIS-2 type substrate then reflowed. The reflowed solder is examined with a stereo microscope at 30X magnification. No more than 2 solder balls larger than one fifth the size of the pattern gap is allowed per gap.

10. Packing:

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	Individual Package	Outer Package		
Unit	Packing	Unit	Packing	
500g	Polyethylene bottle	10kg ; 20kg		
500g	6 oz Catridge	10kg		
800g	Proflow Cassette	8kg ; 16kg	Cardboard Box	
1500g	18 oz Catridge	15kg		

11. Identification:

	Polyethylene bottle	Cardboard
Name	Almit-Solder-Paste SRC HM1 RMA (Ag2) V16L	same as the left
Lot Nr.	(Ex.) 120119-9	dto.
Solder Powder Size	20 - 38 μm	dto.
Date of Mfg.	(Ex.) 19.01.2012	dto.
Net Weight	(Ex.) 500g	dto.
Maker	Nihon Almit Co. Ltd.	dto.

10. Maker Address:

Nihon Almit Co. Ltd. Almit Bldg., 2-14-2 Yayoicho, Nakano-ku, Tokyo, Japan

- **12.** This product is manufactured, using all guaranteed materials according to the legal law regulations.

13. Shelf Life:

Up to two (2) years from the manufactured date (lot number).